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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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9.9mm (0.39INCH) SINGLE DIGIT NUMERIC DISPLAY

Yellow

Part Number: SA39-12YWA

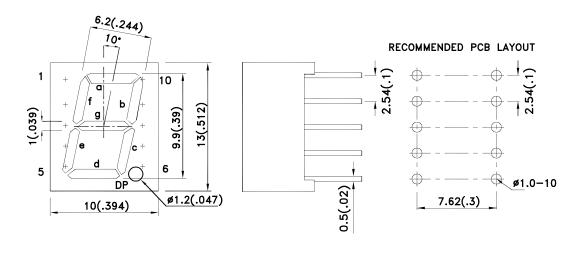
Features

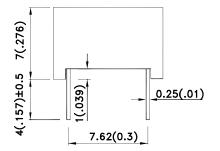
- 0.39 inch digit height.
- Low current operation.
- Excellent character appearance.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

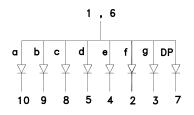
Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram







Notes



2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 SPEC NO: DSAD2251
 REV NO: V.11
 DATE: MAR/30/2011
 PAGE: 1 OF 6

 APPROVED: WYNEC
 CHECKED: Joe Lee
 DRAWN: J.Yu
 ERP: 1301000424

Selection Guide

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description
		,,	Min.	Тур.	
SA39-12YWA	Yellow (GaAsP/GaP)	White Diffused	1400	3000	Common Anode, Rt. Hand Decimal.

Note:

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
IR	Reverse Current	Yellow		10	uA	V _R =5V

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

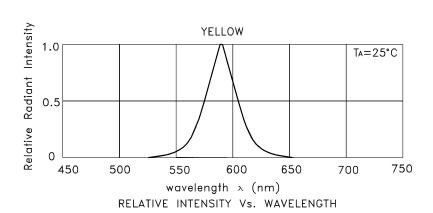
Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating / Storage Temperature -40°C To +85°C				
Lead Solder Temperature[2]	er Temperature[2] 260°C For 3-5 Seconds			

- Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.

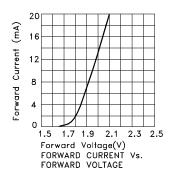
SPEC NO: DSAD2251 **REV NO: V.11** DATE: MAR/30/2011 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: J.Yu ERP: 1301000424

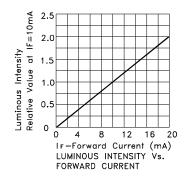
^{1.} Luminous intensity/ luminous Flux: +/-15%.

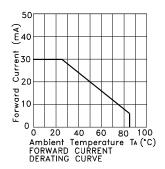


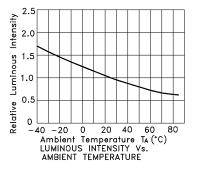
Yellow

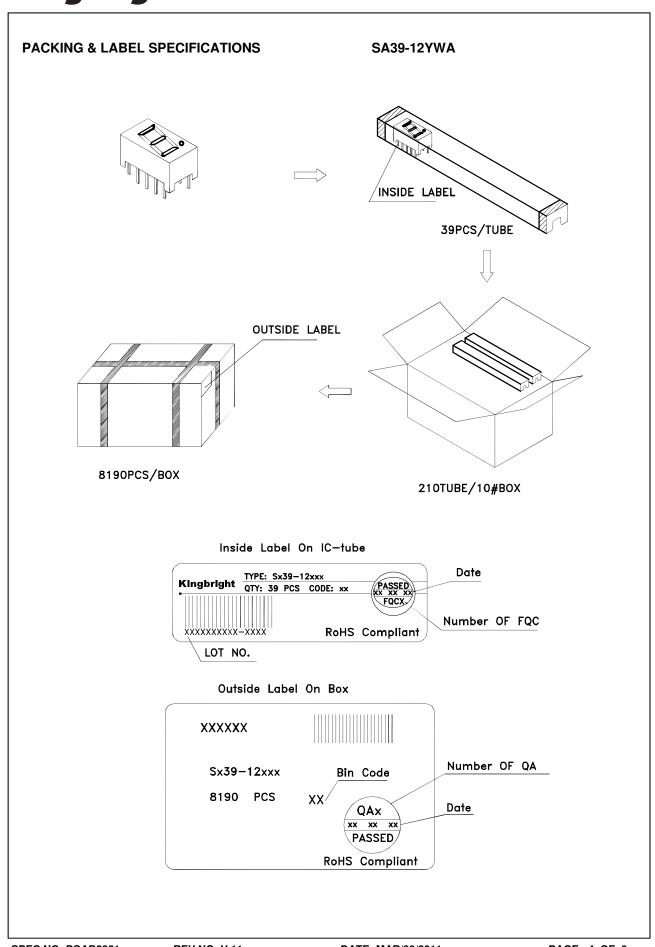
SA39-12YWA









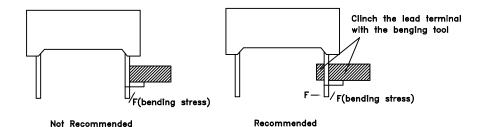


SPEC NO: DSAD2251 APPROVED: WYNEC REV NO: V.11 CHECKED: Joe Lee DATE: MAR/30/2011 DRAWN: J.Yu PAGE: 4 OF 6 ERP: 1301000424

THROUGH HOLE DISPLAY MOUNTING METHOD

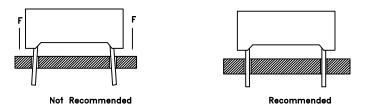
Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



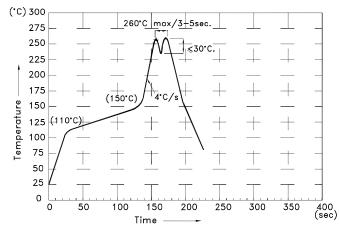
Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1. Recommend the wave temperature 245°C \sim 260°C. The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top—surface temperature should be kept below 105° C
- 5.No more than once.

SPEC NO: DSAD2251 **REV NO: V.11** DATE: MAR/30/2011 PAGE: 5 OF 6 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: J.Yu ERP: 1301000424

Soldering General Notes:

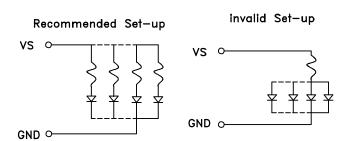
- a. Through—hole displays are incompatible with reflow soldering.
- b. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



SPEC NO: DSAD2251 APPROVED: WYNEC REV NO: V.11 CHECKED: Joe Lee DATE: MAR/30/2011 DRAWN: J.Yu PAGE: 6 OF 6 ERP: 1301000424